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TABLE OF CONTENTS

SESSION 1: THERMAL PHENOMENA ON THE NANO SCALE

Nanoscale Thermal Transport and Phonon Dynamics in Ultra-thin Si Based Nanostructures	10
<i>M. R. Wagner, E. Chávez-Ángel, J. Gomis-Bresco, J. S. Reparaz, A. Shchepetov, M. Prunnila, J. Ahopelto, F. Alzina, C. M. Sotomayor-Torres</i>	
Investigation of High Gigahertz Acoustic Phonon Lifetimes in Thin Silicon Membranes	13
<i>Martin Schubert, Martin Grossmann, Matthias Klingele, Oliver Ristow, Mike Hettich, Thomas Dekorsy</i>	
Investigation of the Thermal Behaviour of Thin Crystalline Silicon Solar Cells	15
<i>Balázs Plesz, Sándor Ress</i>	
The Nondestructive Thermoacoustic Method of Determination of the Air-tightness of Metal Packagings of Transistors	21
<i>Maciej Kubicki, Mirosław Malinski</i>	

SESSION 2: DESIGN AND SIMULATION

Multi-physics Modelling for Power Electronics Modules - Current Status and Future Challenges.....	28
<i>Chris Bailey</i>	
Stochastic Thermal Modeling by Polynomial Chaos Expansion.....	33
<i>Lorenzo Codecasa, Luca Di Renzo</i>	
Electro-thermal Co-design of Chip-package-board Systems	39
<i>Christoph Sohrmann, Andy Heinig, Michael Dittrich, Roland Jancke, Peter Schneider</i>	

Session 3: Characterization

Toolset for Measuring Thermal Behavior of FPGA Devices.....	48
<i>Pawel Weber, Maciej Zagrabski, Bartosz Wojciechowski, Krzysztof S. Berezowski, Maciej Nikodem, Krzysztof Kępa</i>	
Thermal Conductivity Measurements with the 3o Method and Scanning Thermal Microscopy.....	54
<i>Wassim Jaber, Ali Assy, Stéphane Lefèvre, Séverine Gomès, Pierre-Olivier Chapuis</i>	
Thermal Conductivity of Isotopically Enriched Silicon Carbide.....	58
<i>Björn Lundqvist, Peter Raad, Milan Yazdanfar, Pontus Stenberg, Rickard Liljedahl, Pavel Komarov, Niklas Rorsman, J. Åger III, Olle Kordina, Ivan Ivanov, Erik Janzen</i>	

SESSION 4: THERMAL (INTERFACE) MATERIALS

Polymers in Power Electronics – Performance of Thermal Interface Materials.....	64
<i>André Zimmermann, Klaus-Volker Schütt</i>	
Development and Fabrication of a Thin Film Thermo Test Chip and Its Integration Into a Test System for Thermal Interface Characterization	67
<i>M. Aboras, G. Engelmann, D. May, M. Rothermund, R. Schacht, B. Wunderle, H. Oppermann, T. Winkler, S. Rzepka, B. Michel</i>	
Effect of Nanostructuration on the Thermal Conductivity of Thermoelectric Materials.....	73
<i>Stéphane Grauby, Etienne Puyoo, Miguel Munoz Rojo, Marisol Martin-Gonzalez, Wilfrid Claeys, Stefan Dilhaire</i>	

SESSION 6: THERMAL METROLOGY

Transient Thermal Techniques As Failure Analytical Tool.....	82
<i>D. May, B. Wunderle, R. Schacht</i>	
Practical Aspects of Thermal Transient Testing in Live Digital Circuits	87
<i>Gergely Nagy, Péter Horváth, András Poppe</i>	
Improving the Accuracy of Junction Temperature Measurement with the Square-root-t Method	92
<i>Christian Herold, Menia Beier, Josef Lutz, Alexander Hensler</i>	

Thermal Conductivity Reduction in Si Free-standing Membranes Investigated Using Raman Thermometry	95
<i>J. S. Reparaz, E. Chávez-ángel, J. Gomis-Bresco, M. R. Wagner, A. Shchepetov, M. Prunnila, J. Ahopelto, F. Alzina, C. M. Sotomayor Torres</i>	

SESSION 7: RELIABILITY

Solder Joint Lifetime of Rapid Cycled LED Components.....	98
<i>Wendy Luiten</i>	
Mean-time-to-crack Model of Microbump Interconnect in FCGBA Package Under Thermal Cyclic Test.....	104
<i>Chien-Chang Chen, Wei-Chen Wu, Ching-Yu Chin, Hung-Ming Chen, Vito Lin, Eason Chen</i>	
Stress Impact of Thermal-mechanical Loads Measured with the Stress Chip	110
<i>F. Schindler-Saejkow, F. Rost, A. Otto, J. Keller, T. Winkler, B. Wunderle, B. Michel, S. Rzepka</i>	
Optimisation of Low Dissipation Micro-hotplates – Thermo-mechanical Design and Characterisation	116
<i>Ferenc Bíró, Csaba Dürös, Zoltán Hajnal, Andrea Edit Pap, István Bársány</i>	
Lifetime of CMOS Circuits Evaluation by Means of Electro-thermal Simulations	122
<i>Maroua Garcí, Jean-Baptiste Kammerer, Luc Hebrard</i>	

SESSION 8: THERMAL MANAGEMENT CONCEPTS

Thermal Transient Characterization of Semiconductor Devices with Multiple Heat Sources – Fundamentals for a New Thermal Standard.....	128
<i>Dirk Schweitzer</i>	
Thermal Management Challenges in the Passive Cooling of Handheld Devices	135
<i>Guy Wagner, William Maltz</i>	
Power and Thermal Constraints of Modern System-on-a-chip Computer.....	141
<i>Efraim Rotem, Ran Ginosar, Avi Mendelson, Uri C. Weiser</i>	
Experimental Investigation of Uninterrupted and Interrupted Microchannel Heat Sinks	147
<i>Ayse Gozde Ulu Soysal, Cuneyt Sert, Almila Guvenc Yazicioglu</i>	

SESSION 9: DESIGN AND SIMULATION II

Convolution Based Compact Thermal Model for 3D-ICs: Methodology and Accuracy Analysis	152
<i>Federica Lidia Teresa Maggioni, Herman Oprins, Eric Beyne, Ingrid De Wolf, Tine Baelmans</i>	
Dynamic Sub-compact Model and Global Compact Model Reduction for Multichip Components	158
<i>Cheikh Tidiane Dia, Eric Monier-Vinard, Najib Laraqi, Valentin Bissuel, Olivier Daniel</i>	
Novel Approach to Compact Modeling for Nonlinear Thermal Conduction Problems	164
<i>Lorenzo Codecasa</i>	

SESSION 10: SOLID STATE LIGHTNING/LED

Inline Rth Control: Fast Thermal Transient Evaluation for High Power LEDs.....	172
<i>Thomas Dannerbauer, Thomas Zahner</i>	
Improving Thermal Conductivity of Polymer Composites in Embedded LEDs Systems.....	176
<i>Joan Yu, Giovanni Cennini</i>	
Study on Thermal Performance of High Power LED Employing Aluminium Filled Epoxy Composite As Thermal Interface Material.....	181
<i>P. Anithambigai, S. Shanmugan, D. Mutharasu, T. Zahner, D. Lacey</i>	
The Influence of Mutual Thermal Interactions Between Power LEDs on Their Characteristics	188
<i>Krzysztof Górecki</i>	
Influence of Different Characterization Parameters on the Accuracy of LED Board Thermal Models for Retrofit Bulbs.....	194
<i>Xavier Jordà, Xavier Perpiñà, Miquel Vellvehi, Wim Hertog, Mariano Perálvarez, Josep Carreras</i>	

SESSION 11: POWER ELECTRONICS

Impact of Nonlinearities in Boundary Conditions on Device Compact Thermal Models.....	202
<i>Marcin Janicki, Tomasz Torzewicz, Andras Vass-Varnai, Andrzej Napieralski</i>	
Thermal Design of a High Current Circuit Board for Automotive Applications.....	206
<i>Raúl Mrofško, Christoph Neeb, Thomas Hofmann, Alexander Neumann, Jürgen Keller</i>	
Fully-coupled 3D Electro-thermal Field Simulator for Chip-level Analysis of Power Devices	210
<i>Wim Schoenmaker, Olivier Dupuis, Bart De Smedt, Peter Meuris, Jiri Ocenasek, Wim Verhaegen, Dundar Dumlugol, Martin Pfost</i>	
Generation of Electro-thermal Models of Integrated Power Electronics Modules Using a Novel Synthesis Technique	216
<i>Giuseppe Greco, Giovanni Vinci, Angelo Raciti, Davide Cristaldi</i>	

SESSION 12: FLUIDICS

Hybrid Porous Media and Fluid Domain Modeling Strategy to Optimize a Novel Staggered Fin Heat Sink Design.....	224
<i>Ningkang Li, Gerd Schlottig, Marco De-Fazio, Chander Shekhar Sharma, Manish Tiwari, Roberto Brioschi, Dimos Poulikakos, Thomas Brunschwiler</i>	
Numerical Basis and Validation of CAD-centric CFD: Honeycomb Heatsink Study.....	231
<i>Travis Mikjaniec, Paul Blais, John Parry</i>	
Co-design of Multicore Architectures and Microfluidic Cooling for 3D Stacked ICs	237
<i>Zhimin Wan, He Xiao, Yogendra Joshi, Sudhakar Yalamanchili</i>	

SPECIAL SESSION 1: SMART POWER

Free Standing Thermal Interface Material Based on Vertical Arrays Composites	244
<i>E. Leveugle, L. Divay, H. Le Khanh, J. Daon, E. Chastaing, P. Le Barny, A. Ziae</i>	
Controlling the Density of CNTs by Different Underlayermaterials in PECVD Growth.....	248
<i>Liang Xu, Di Jiang, Yifeng Fu, Shantung Tu, Johan Liu</i>	
Double-sided Cooling and Thermo-electrical Management of Power Transients for Silicon Chips on DCB-substrates for Converter Applications: Design, Technology and Test.....	253
<i>B. Wunderle, C.-A. Manier, M. Abo Ras, M. Springborn, D. May, H. Oppermann, M. Toepper, R. Mrossko, T. Xhonneux, T. Caroff, W. Maurer, R. Mitova</i>	
Transient Cooling of Power Electronic Devices Using Thermoelectric Coolers Coupled with Phase Change Materials.....	262
<i>T. Caroff, R. Mitova, B. Wunderle, J. Simon</i>	
Novel High Sensitivity Sensor Structures for Temperature Monitoring of GAN Based MMICs	268
<i>Alexandru Muller, George Konstantinidis, Adrian Dinescu, Valentin Buiculescu, Alexandra Stefanescu, Alina Cismaru, Ioana Giangu, George Stavrinidis, Antonis Stavrinidis, Afshin Ziae</i>	
Failure Prediction of IGBT Modules Based on Power Cycling Tests.....	270
<i>Zoltan Sarkany, Andras Vass-Varnai, Gusztav Hantos, Marta Renz</i>	

SPECIAL SESSION 2: NANOTHERM

Integrating Advanced Interconnect Technologies in a High Power Lighting Application: First Steps.....	276
<i>Sander Noijen, Sebastian Fritzsche, Andreas Steffen Klein, Andras Poppe, Gerard Kums, Olaf Van Der Sluis</i>	
Reliability of Advanced Thermal Interface Technologies Based on Sintered Die-attach Materials	281
<i>Jens Heilmann, Ivan Nikitin, Daniel May, Klaus Pressel, Bernhard Wunderle</i>	
Modelling of Graphene and Few-layer Graphene Heat Spreaders for Hot-spot Cooling	283
<i>Yuxiang Ni, Jose Ordóñez-Miranda, Yann Chalopin, Sebastian Volz</i>	
Fabrication and Characterization of a Metal Matrix Polymer Fibre Composite for Thermal Interface Material Applications.....	286
<i>Carl Zandén, Xin Luo, Lilei Ye, Johan Liu</i>	

SESSION 5: POSTER

The Effect of Heat Treatment on Spin-on Oxide Glasses in Solar Cell Application	297
<i>Eniko Bányi, Árpád Földváry, Márta Rencz</i>	
Thermal Model Generalization of Infrared Radiation Sensors	301
<i>Gy. Bognár, P. G. Szabó</i>	
Self-heating of Nano-scale SOI MOSFETs: TCAD and Molecular Dynamics Simulations	305
<i>Alex Burenkov, Viktor Belko, Jürgen Lorenz</i>	
Compact Electro-thermal Models of Interconnects	309
<i>Lorenzo Codecasa</i>	
Investigation of Delphi Compact Thermal Model Style for Modeling Surface-mounted Soft Magnetic Composite Inductor	315
<i>Eric Monier-Vinard, Valentin Bisuel, Cheikh Tidiane Dia, Olivier Daniel, Najib Laraqi</i>	
Thermal Characterization of Multichip Structures	319
<i>Ferenc Ender, Gusztáv Hantos, Dirk Schweitzer, Péter G. Szabó</i>	
The Compact Thermal Model of the Pulse Transformer	323
<i>Krzesztof Gorecki, Ma-gorzata Rogalska</i>	
Heat Flux Sensor for Power Loss Measurements of Switching Devices	327
<i>Demetrio Iero, Francesco G. Della Corte, Giuseppe Fiorentino, Pasqualina M. Sarro, B. Morana</i>	
Empirical Feasibility Assessment of Energy Scavenging Opportunity in Compact Mobile Computers	331
<i>Muhammad Azhar Ali Khan, Ali Muhtaroglu</i>	
Non-linear Thermal Simulations of Semiconductor Devices on System Level	335
<i>Vladimír Košel, Monika Schipani, Ehrenfried Seebacher</i>	
Proposal of New Thermal Resistance for Light-emitting Diodes	339
<i>Byungjin Ma, Kwanhoon Lee</i>	
Combined Method for Thermal Characterization of High Power Semiconductors	341
<i>Enrico Merten, Mohamad Abo Ras, Tobias Von Essen, Ralph Schacht, Daniel May, Thomas Winkler, Bernd Michel</i>	
Thermal-electronic Integrated Logic	344
<i>János Mizsei, Jyrki Lappalainen, Márton C. Bein</i>	
Approach for Reliability of Thermal Interface Materials in Battery Cell Sensors	348
<i>Torsten Nowak, Matthias Müller, Hans Walter, Ole Hölk, Felix Wüst, Olaf Wittler, Klaus-Dieter Lang</i>	
Low Voltage Fully Integrated DC-DC Converter for Self-Powered Temperature Sensors	N/A
<i>Manula Randhika Pathirana, Ali Muhtaroglu</i>	
Single Kernel Electro-thermal IC Simulator	356
<i>Philippe Raynaud</i>	
SrTiO₃ Thin Films As High Efficient Thermoelectric Materials	359
<i>S. Bhansali, W. Khunsin, J. S. Reparaz, M. R. Wagner, J. Roqueta, J. Santiso, B. Abad Mayor, P. Díaz-Chao, M. Martin-Gonzalez, C. M. Sotomayor Torres</i>	
Electronics Cooling by Extended Surface: Refractive Index Changes Flow Visualization of the Natural Convection Heat Transfer	361
<i>C. Sapia, G. Sozio</i>	
Parametric Transient Thermo-electrical PSPICE Model for a Power Cable	368
<i>Ralph Schacht, Sven Rzepka, Bernd Michel</i>	
Characterization and Kinetic Monitoring of the Reactions Between TiAlY Phases in Ti-Al Based Ohmic Contacts on N-type GaN by Differential Scanning Calorimetry (DSC)	372
<i>Nicolas Thierry-Jebali, Rodica Chiriac, Christian Brylinski</i>	
Logi-thermal Simulation Using High-resolution Temperature Dependent Delay Models	376
<i>András Timár, Márta Rencz</i>	
In-situ Measurements of Material Thermal Parameters for Accurate LED Lamp Thermal Modelling	381
<i>Miquel Vellvehi, Xavier Perpiñà, Xavier Jordà, Robert J. Werkhoven, Jos M. G. Kunen, Jiri Jakovenko, Peter Bancken, Pieter J. Bolt</i>	
Analysis of the Effectiveness of Core Swapping in Modern Multicore Processors	385
<i>Piotr Zajac, Michał Szermer, Marcin Janicki, Cezary Maj, Piotr Pietrzak, Andrzej Napieralski</i>	
Author Index	